

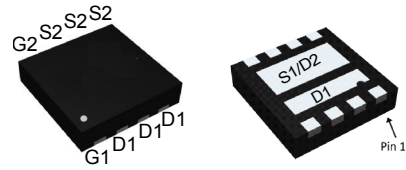
Features

- 20V/13A
 $R_{DS(ON)}=5.2m\Omega(\text{typ.})@V_{GS}=4.5V$
 $R_{DS(ON)}=6.7m\Omega(\text{typ.})@V_{GS}=2.5V$
- 100% UIS + R_g Tested
- Reliable and Rugged
- Lead Free and Green Devices Available
 (RoHS Compliant)

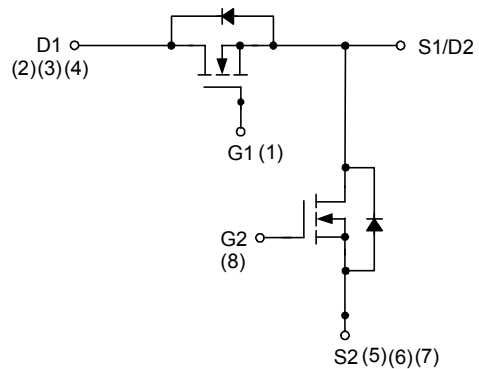
Applications

- Power Management in Notebook Computer, Portable Equipment and Battery Powered Systems.

Pin Description



TDFN3x3-8_EP2



N-Channel MOSFET

Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ Unless Otherwise Noted)

Symbol	Parameter	Rating	Unit
Common Ratings			
V_{DSS}	Drain-Source Voltage	20	V
V_{GSS}	Gate-Source Voltage	± 12	
T_J	Maximum Junction Temperature	150	$^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55 to 150	
I_S	Diode Continuous Forward Current	$T_C=25^\circ\text{C}$ 13	A
I_D	Continuous Drain Current	$T_C=25^\circ\text{C}$ 13	A
		$T_C=100^\circ\text{C}$ 5.2	
I_{DM}^b	Pulsed Drain Current	$T_C=25^\circ\text{C}$ 39	A
P_D	Maximum Power Dissipation	$T_C=25^\circ\text{C}$ 18	W
		$T_C=100^\circ\text{C}$ 7	
$R_{\theta JC}$	Thermal Resistance-Junction to Case	Steady State 7	$^\circ\text{C/W}$
I_D	Continuous Drain Current	$T_A=25^\circ\text{C}$ 8	A
		$T_A=70^\circ\text{C}$ 6	
I_{DM}^b	Pulsed Drain Current	$T_A=25^\circ\text{C}$ 32	A
P_D	Maximum Power Dissipation	$T_A=25^\circ\text{C}$ 1.6	W
		$T_A=70^\circ\text{C}$ 1	
$R_{\theta JA}^c$	Thermal Resistance-Junction to Ambient	$t \leq 10\text{s}$ 43	$^\circ\text{C/W}$
		Steady State 80	
I_{AS}^d	Avalanche Current, Single pulse	$L=0.1\text{mH}$ 9	A
E_{AS}^d	Avalanche Energy, Single pulse	$L=0.1\text{mH}$ 4.1	mJ

Note a : Maximum continuous current is limited by bonding wire.

Note b : Pulse width is limited by maximum junction temperature.

Note c : Surface mounted on 1in^2 pad area, steady state $t = 999\text{s}$.

Note d : UIS tested and pulse width limited by maximum junction temperature (initial temperature $T_j=25^\circ\text{C}$).

Electrical Characteristics ($T_A = 25^\circ\text{C}$ unless otherwise noted)

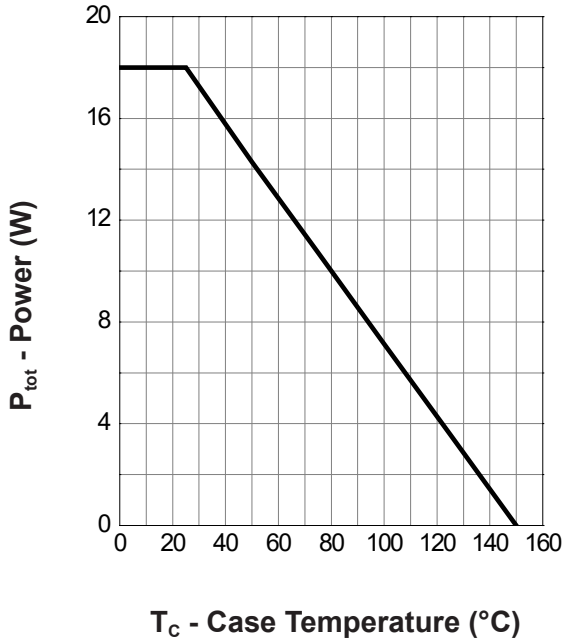
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_{DS}=250\mu A$	20	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=16V, V_{GS}=0V$ $T_J=85^\circ\text{C}$	-	-	1 30	μA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_{DS}=250\mu A$	0.4	0.75	1	V
I_{GSS}	Gate Leakage Current	$V_{GS}=\pm 12V, V_{DS}=0V$	-	-	± 100	nA
$R_{DS(ON)}^e$	Drain-Source On-state Resistance	$V_{GS}=4.5V, I_{DS}=4A$ $T_J=125^\circ\text{C}$	-	5.2 7	7 -	m Ω
		$V_{GS}=2.5V, I_{DS}=3A$	-	6.7	8	
Gfs	Forward Transconductance	$V_{DS}=5V, I_{DS}=5A$	-	10	-	S
Diode Characteristics						
V_{SD}^e	Diode Forward Voltage	$I_{SD}=2A, V_{GS}=0V$	-	0.75	1.1	V
t_{rr}	Reverse Recovery Time	$I_{SD}=4A, dI_{SD}/dt=100A/\mu s$	-	4.8	-	ns
t_a	Charge Time		-	4	-	
t_b	Discharge Time		-	8.8	-	
Q_{rr}	Reverse Recovery Charge		-	3.2	-	
Dynamic Characteristics^f						
R_G	Gate Resistance	$V_{GS}=0V, V_{DS}=0V, F=1\text{MHz}$	-	2	4	Ω
C_{iss}	Input Capacitance	$V_{GS}=0V,$ $V_{DS}=10V,$ Frequency=1.0MHz	-	2336	2697	pF
C_{oss}	Output Capacitance		-	266	-	
C_{rss}	Reverse Transfer Capacitance		-	178	-	
$t_{d(ON)}$	Turn-on Delay Time	$V_{DD}=10V, R_L=10\Omega,$ $I_{DS}=1A, V_{GEN}=4.5V,$ $R_G=6\Omega$	-	4	8	ns
t_r	Turn-on Rise Time		-	13	24	
$t_{d(OFF)}$	Turn-off Delay Time		-	22	40	
t_f	Turn-off Fall Time		-	5	9	
Gate Charge Characteristics^f						
Q_g	Total Gate Charge	$V_{DS}=10V, V_{GS}=10V,$ $I_{DS}=4A$	-	12	17	nC
Q_g	Total Gate Charge	$V_{DS}=10V, V_{GS}=4.5V,$ $I_{DS}=4A$	-	6.2	-	
Q_{gth}	Threshold Gate Charge		-	0.3	-	
Q_{gs}	Gate-Source Charge		-	0.6	-	
Q_{gd}	Gate-Drain Charge		-	2	-	

 Note e : Pulse test ; pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.

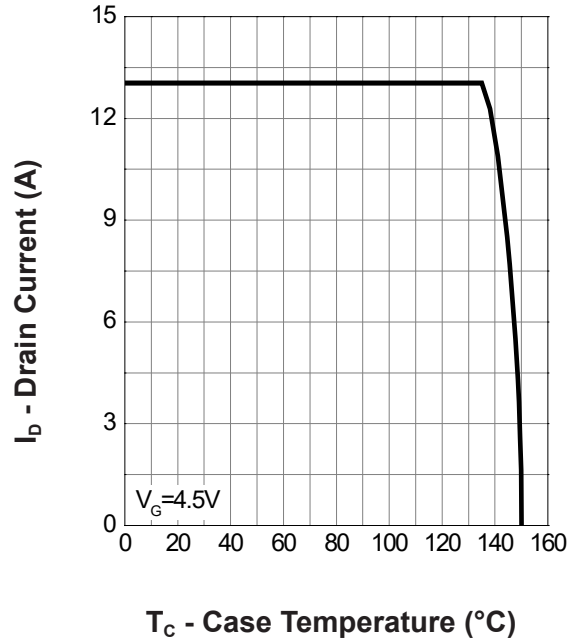
Note f : Guaranteed by design, not subject to production testing.

Typical Operating Characteristics

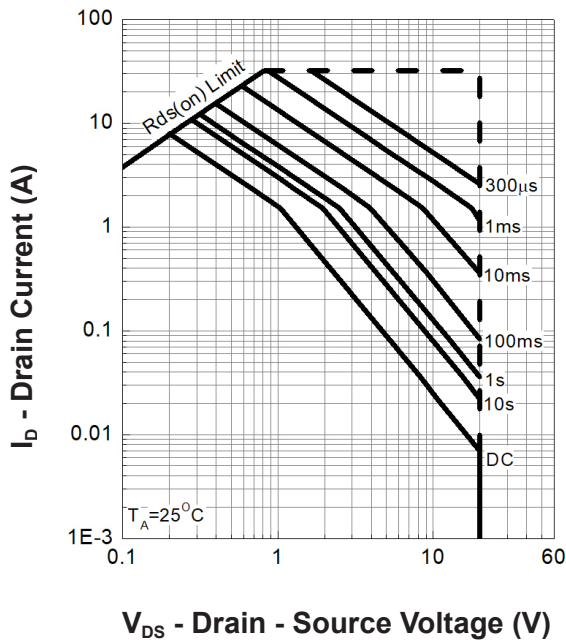
Power Dissipation



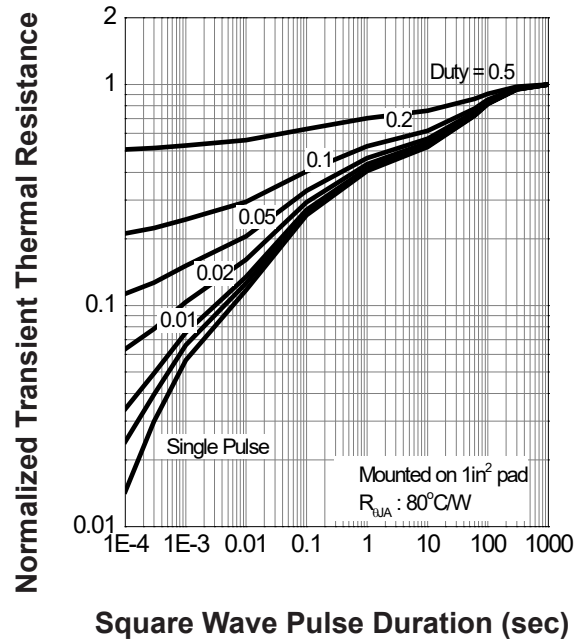
Drain Current



Safe Operation Area

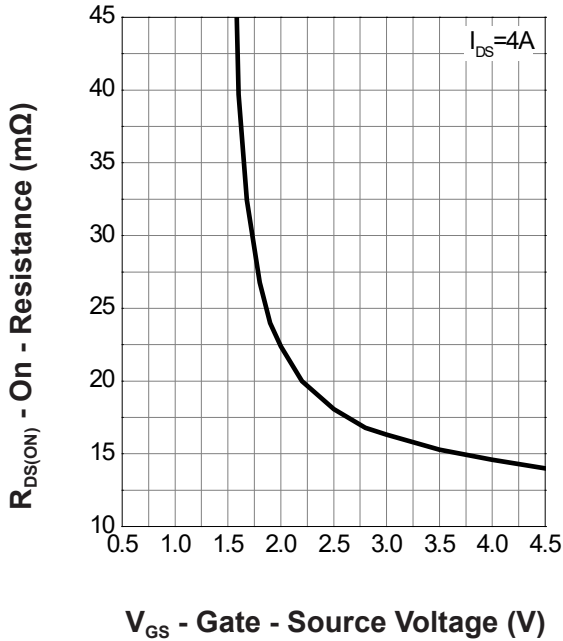


Thermal Transient Impedance

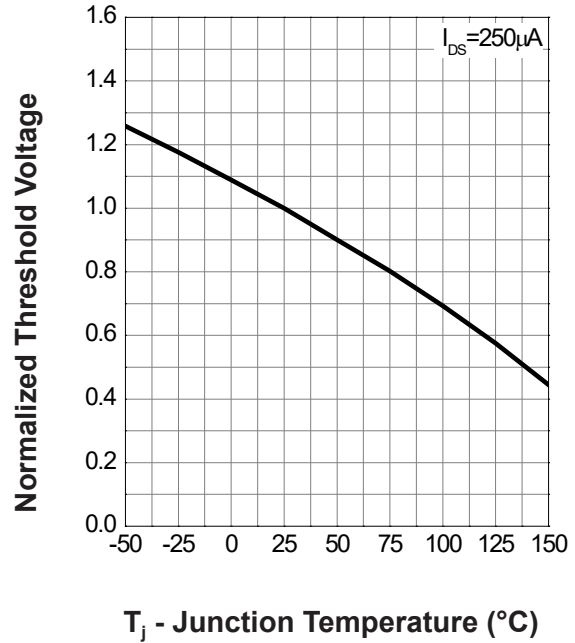


Typical Operating Characteristics(Cont.)

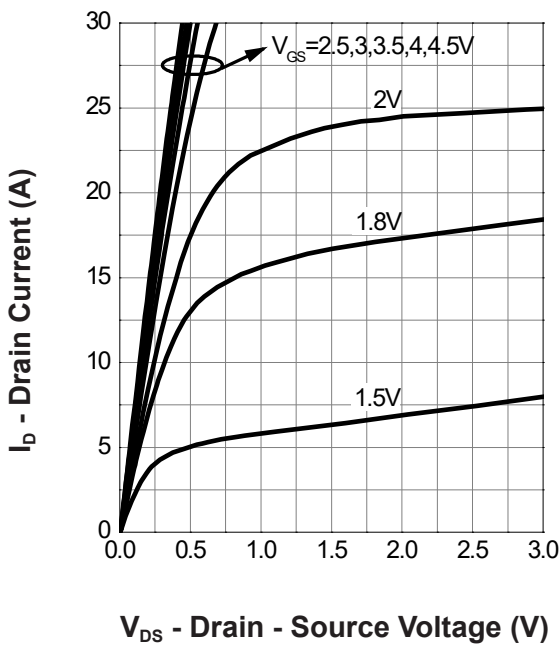
Gate-Source On Resistance



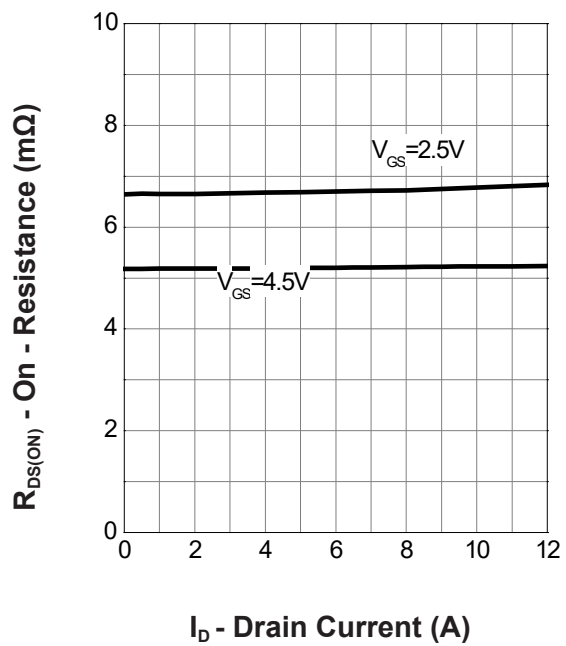
Gate Threshold Voltage

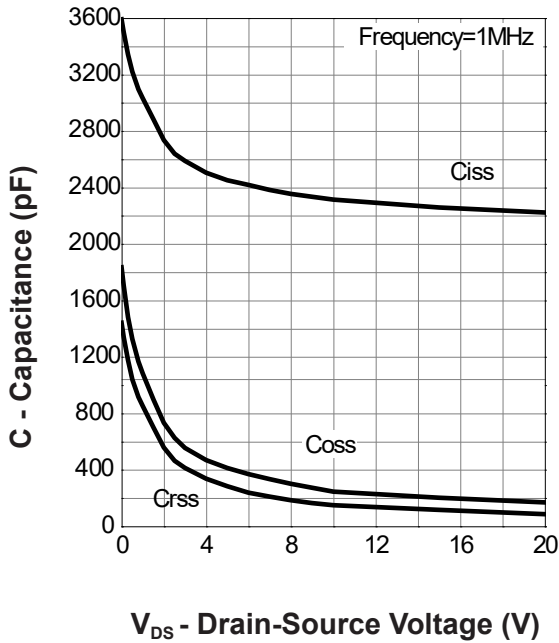
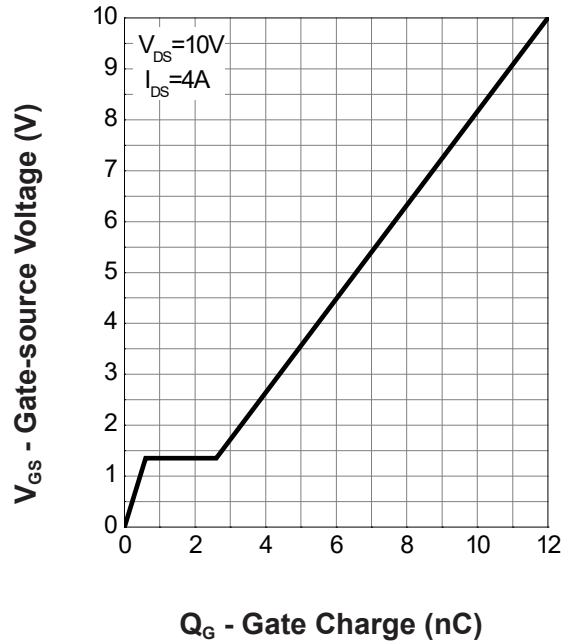
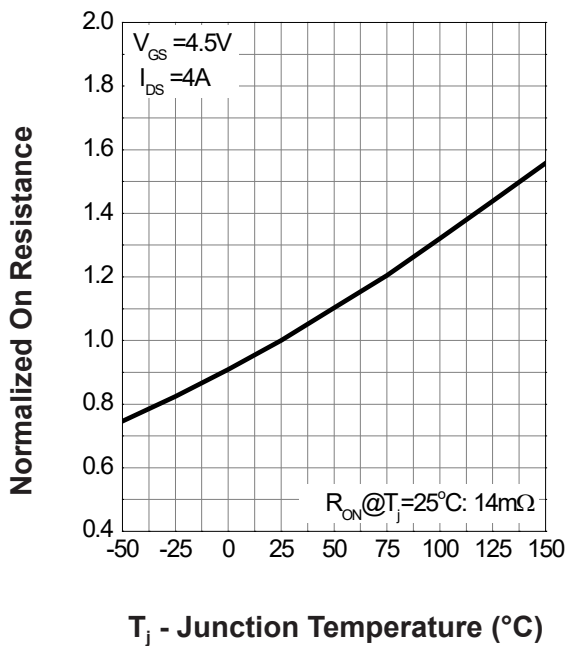
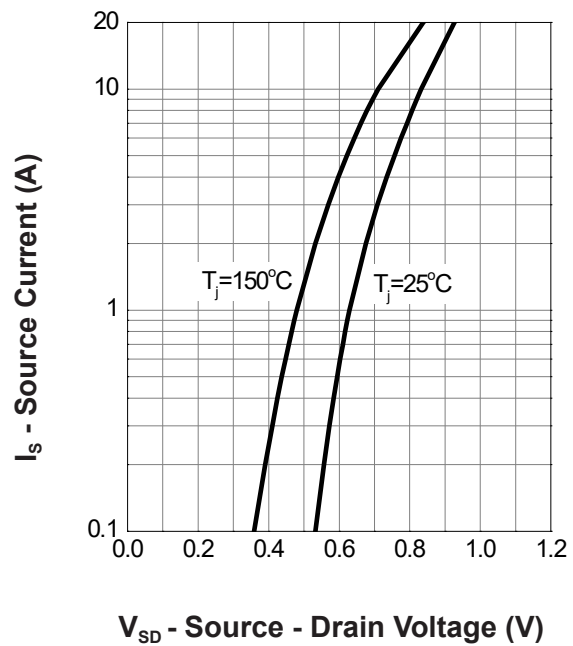


Output Characteristics

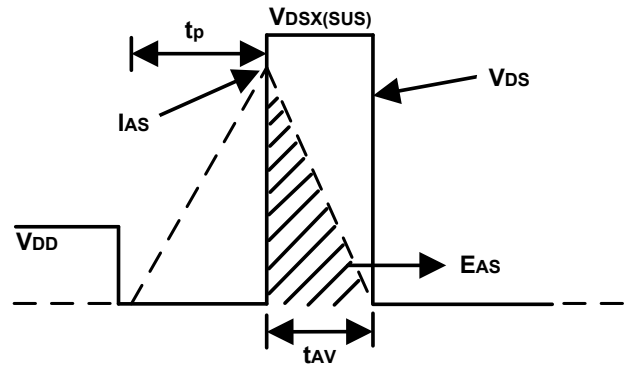
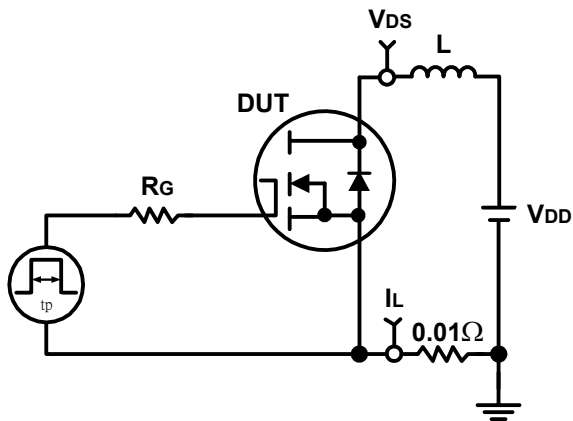


Drain-Source On Resistance

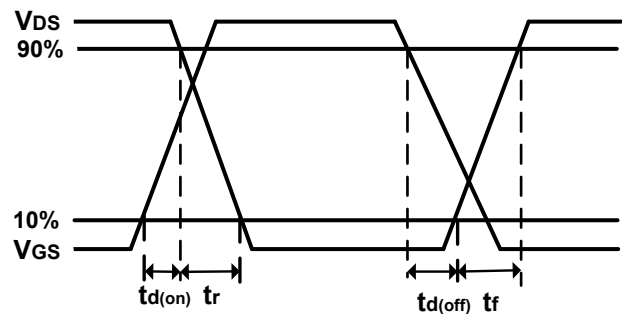
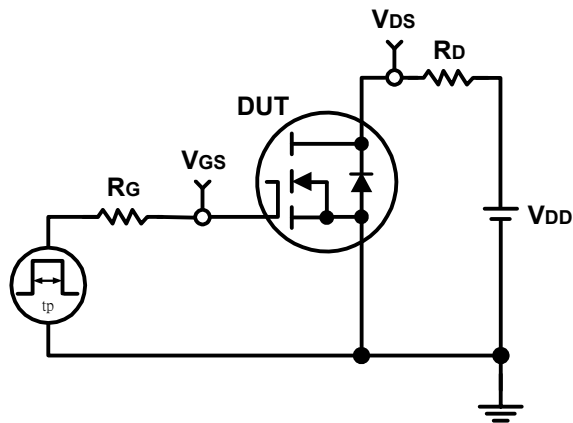


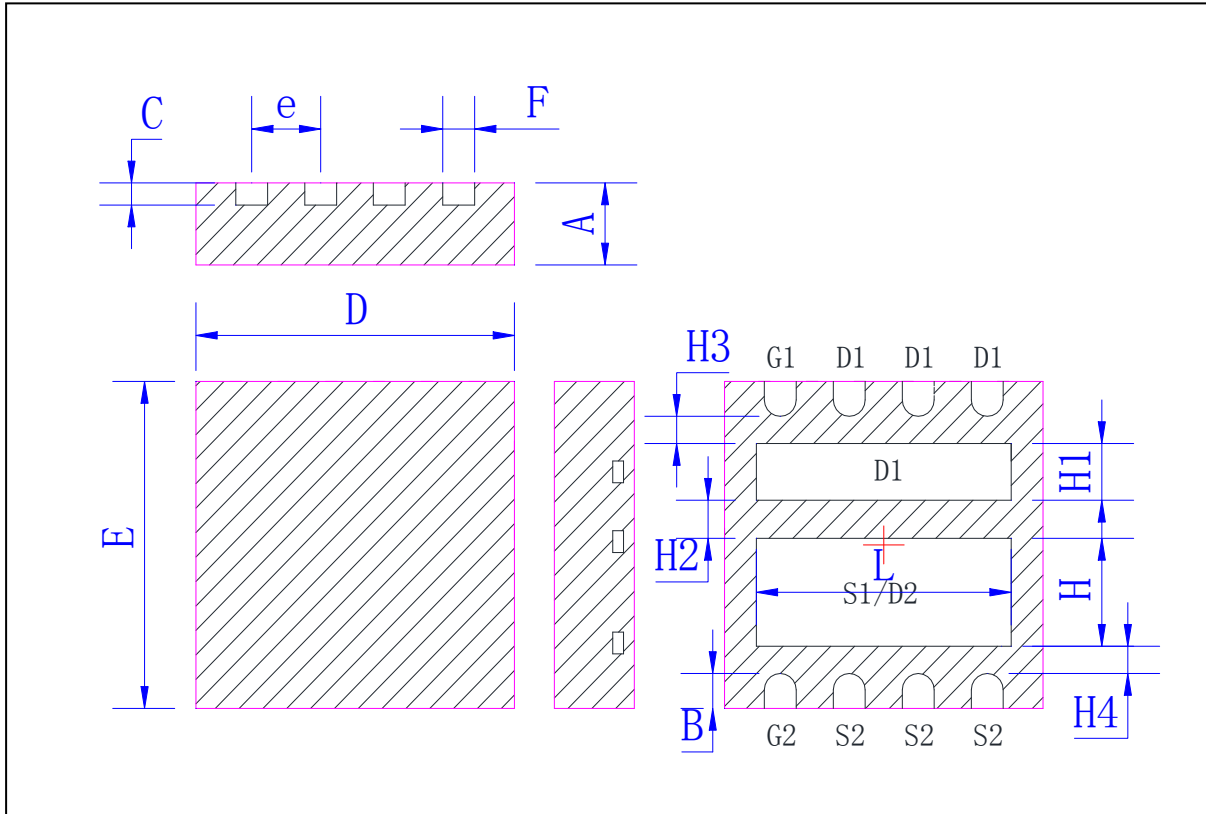
Typical Operating Characteristics(Cont.)
Capacitance

Gate Charge

Drain-Source On Resistance

Source-Drain Diode Forward


Avalanche Test Circuit and Waveforms



Switching Time Test Circuit and Waveforms



TDFN3*3-8_EP2 OUTLINE


Symbol	Min	Typ	Max
A	0.70	0.75	0.80
B	0.27	0.32	0.37
C	0.153	0.203	0.253
D	2.90	3.00	3.10
E	2.90	3.00	3.10
e	0.60	0.65	0.70
F	0.25	0.30	0.35
H	0.89	0.99	1.09
H1	0.42	0.52	0.62
H2	0.25	0.35	0.45
H3	0.15	0.25	0.35
H4	0.15	0.25	0.35
L	2.30	2.40	2.50